

024-23-04

Express Mail No. EV 346 810 864 US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: B. GHYSELEN et al

Confirmation No. 2668

Application No: 10/726,039

Group Art Unit: 2812

Filing Date: December 1, 2003

Examiner:

For: RECYCLING OF A WAFER COMPRISING  
A BUFFER LAYER AFTER HAVING  
SEPARATED A THIN LAYER THEREFROM BY  
MECHANICAL MEANS

Atty. Docket No.: 4717-8600

**INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

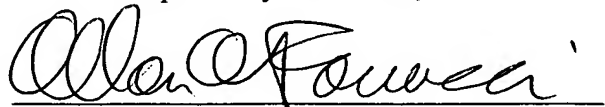
Pursuant to applicants' duty of disclosure under 37 C.F.R. 1.56, applicants submit herewith twelve(12) references for the Examiner's review and consideration. These references were cited in the Preliminary Search Report and a copy is enclosed.

These references are listed on the enclosed Form PTO-1449. It is respectfully requested that these references be made of record in this application by the Examiner's completion and return of the PTO Form 1449.

No fee is believed to be due for the filing of this statement as it is being submitted prior to an initial office action for this application. Should any fees be required, however, please charge such fees to Winston & Strawn LLP Deposit Account No. 50-1814.

Date: 4/2/04

Respectfully submitted,



Allan A. Fanucci (Reg. No. 30,256)

**WINSTON & STRAWN**  
**CUSTOMER NO. 28765**  
(212) 294-3311

Enclosures

NY:858379.1



**LIST OF REFERENCES CITED BY APPLICANT**  
(Use several sheets if necessary)

ATTY. DOCKET NO.:

4717-8600

APPLICATION SERIAL NO.:

10/726, 039

APPLICANT:

Bruno GHYSELEN et al.

FILING DATE:

December 1, 2003

GROUP:

2812

**U.S. PATENT DOCUMENTS**

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA	5,882,987	3/1999	Srikrishnan	438	458	
	AB	6,284,628 B1	9/2001	Kuwahara et al.	438	459	
	AC	6,306,729 B1	10/2001	Sakaguchi et al..	438	458	
	AD	6,326,279 B1	12/2001	Kakizaki et al.	438	406	
	AE	6,468,923 B1	12/2002	Yonehara et al.	438	761	
	AF	2002/0072130 A1	6/2002	Cheng et al.	438	10	

**FOREIGN PATENT DOCUMENTS**

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	AG	EP 0 955 671 A1	11/1999	Europe			X	
	AH	EP 1 039 513 A2	9/2000	Europe			X	
	AI	EP 0 926 709 A2	6/1999	Europe			X	
	AJ	WO 01/11930 A2	2/2001	PCT			X	

**OTHER REFERENCES** (Including Author, Title, Date, Pertinent Pages, Etc.)

	AK	L. J. Huang et al, "SiGe-on-insulator prepared by wafer bonding and layer transfer for high-performance field-effect transistors", Applied Physics Letters, Vol. 78, No. 9, pp. 1267-1269 (2001)
	AL	Q. Y. Tong et al "Extracts of "Semi-conductor on wafer bonding", Science and Technology, Interscience Technology, Wiley Interscience publication, Johnson Wiley & Sons, Inc.
	AM	

**EXAMINER****DATE CONSIDERED**

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.